

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

GBL4005-MS THRU GBL410-MS

Product specification

REVERSE VOLTAGE - 50 to 1000 Volts
FORWARD CURRENT - 4.0 Amperes

FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- Idea for printed circuit board
- Glass passivated Junction chip
- Low reverse leakage
- High forward surge current capability
- High temperature soldering guaranteed 260 C/10 seconds at terminals

MECHANICAL DATA

- **Case** : Molded plastic body
- **Terminals** : Solder plated, solderable per MIL-STD-750,Method 2026
- **Polarity** : Polarity symbol marking on body
- **Mounting Position** : Any
- **Weight**: 0.076 ounces , 2.15 grams

REFERENCE NEWS



Marking

GBL4005-MS	GBL401-MS	GBL402-MS	GBL404-MS
			
GBL406-MS	GBL408-MS	GBL410-MS	
			

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

CHARACTERISTICS	SYMBOL	GBL4005-MS	GBL401-MS	GBL402-MS	GBL404-MS	GBL406-MS	GBL408-MS	GBL410-MS	UNIT
Maximum Recurrent Peak Reverse Voltage	VRRM	50	100	200	400	600	800	1000	V
Maximum RMS Bridge Input Voltage	VRMS	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Output Current @ TA=50°C (Note1)	I(AV)	4.0							A
Peak Forward Surge Current 8.3ms Single Half Sine-Wave Super Imposed on Rated Load	IFSM	125							A
Maximum Forward Voltage Drop Per Bridge Element at 4.0A Peak	VF	1.1							V
Maximum Reverse Current at Rated DC Blocking Voltage	IR	10.0							uA
Maximum Reverse Current at Rated DC Blocking Voltage @ TA =150°C	IR	1.0							mA
Operating Temperature Range	TJ	-55 to +150							°C
Storage Temperature Range	TSTG	-55 to +150							°C

Note:1.Mounting conditions,0.5"lead length maximum.

Ratings And Characteristic Curves

FIG.1-FORWARD DERATING
CURRENT

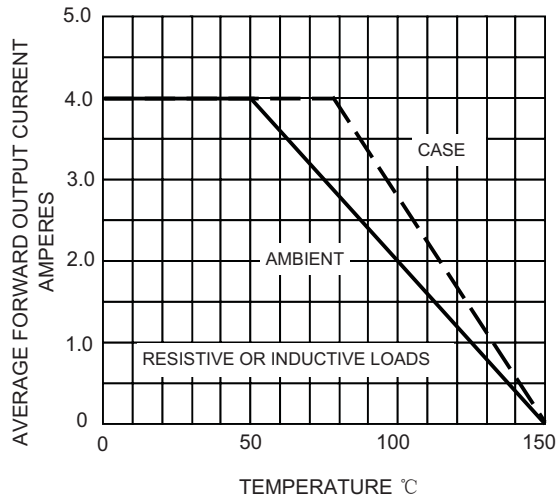


FIG.2-MAXIMUM NON-REPETITIVE SURGE CURRENT

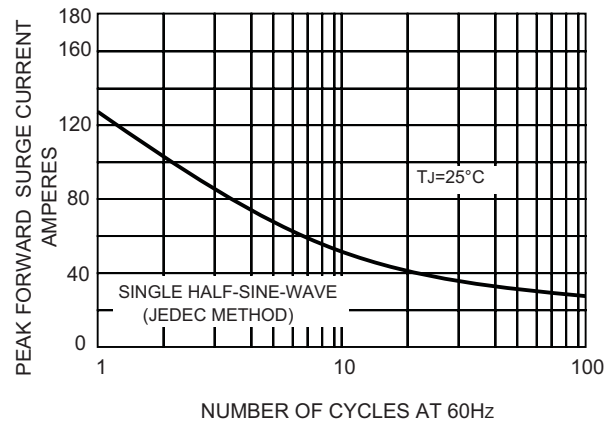


FIG.3-TYPICAL FORWARD CHARACTERISTICS

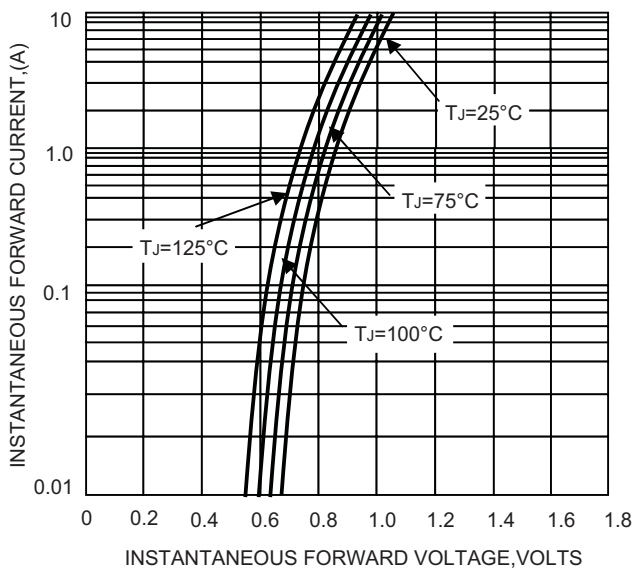
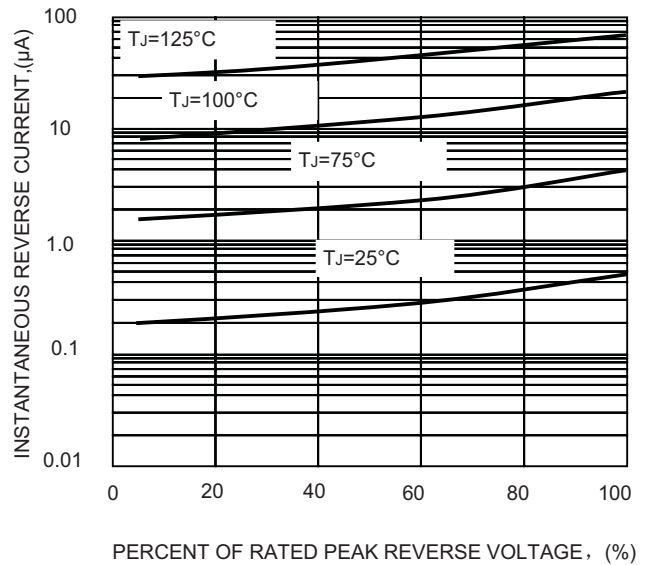
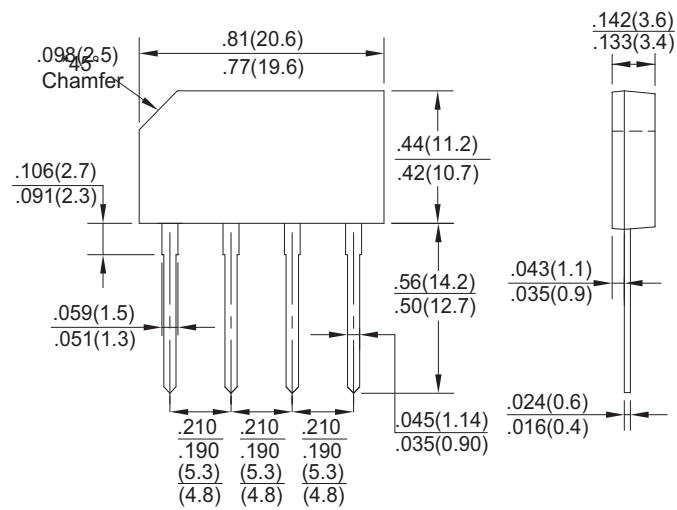


FIG.4-TYPICAL REVERSE CHARACTERISTICS



PACKAGE MECHANICAL DATA

GBL



Dimensions in inches and (millimeters)

REELSPECIFICATION

P/N	PKG	QTY
GBL4005-MS THRU GBL410-MS	GBL	500

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